DERWENT-ACC-NO: 2002-326392

DERWENT-WEEK: 200353

COPYRIGHT 2006 DERWENT INFORMATION LTD

TITLE: Demagnetizer for manufacturing process of semiconductor

package

INVENTOR: HA, JY; HAH, JY

PATENT-ASSIGNEE: AMKOR TECHNOLOGY KOREA INC[AMKON]

PRIORITY-DATA: 1999KR-0064928 (December 29, 1999)

PATENT-FAMILY:

PUB-NO PUB-DATE LANGUAGE PAGES MAIN-IPC KR 379559 B April 10, 2003 N/A 000 H01L 021/50 KR 2001065114 A July 11, 2001 N/A 001 H01L 021/50

APPLICATION-DATA:

PUB-NO APPL-DESCRIPTOR APPL-NO APPL-DATE KR 379559B N/A 1999KR-0064928 December 29, 1999

KR 379559B Previous Publ. KR2001065114 N/A

KR2001065114A N/A 1999KR-0064928 December 29, 1999

INT-CL (IPC): H01L021/50

ABSTRACTED-PUB-NO: KR2001065114A

**BASIC-ABSTRACT:** 

NOVELTY - A demagnetizer for the manufacturing process of a semiconductor package is provided to previously prevent process inferiority in a post process by efficiently removing magnetic force generated from an equipment for the manufacturing process of a semiconductor package in order to prevent foreign matters from being attached to materials.

DETAILED DESCRIPTION - A demagnetizer for the manufacturing process of a semiconductor package is composed of an electromagnetic chuck(1), a rod(2), a driving motor(3), a driving cylinder for forward and backward motion(4), and a driving cylinder for rise and fall(5). The electromagnetic chuck(1), magnetized as power is supplied, generates magnetism. The rod(2) is connected to the electromagnetic chuck(1). The driving motor(3) rotates the rod(2) selectively. The driving cylinder for forward and backward motion(4), connected to the driving motor(3), moves the electromagnetic chuck(1) forward and backward so that it can be located around a magnetism-removed portion. The driving cylinder for rise and fall(5) moves the driving cylinder(4) up and down to separate the electromagnetic chuck(1) from a magnetism generating portion or to make it approached there.

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: MANUFACTURE PROCESS SEMICONDUCTOR PACKAGE

DERWENT-CLASS: U11

EPI-CODES: U11-F02A2;



